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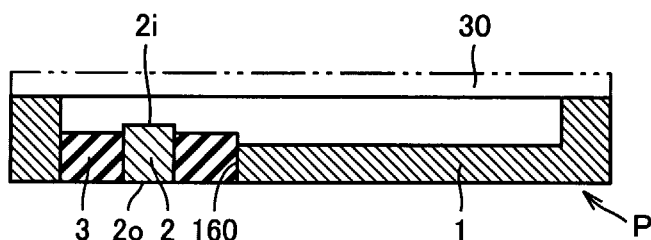
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(54) Title: SURFACE MOUNTING PACKAGE



(57) Abstract: A surface mounting package includes a metal base (1) with a lower surface having a through hole, a metal lead (2) arranged to be inserted into the through hole, an insulating material (3) filling in an internal space defined by the metal base (1), a cap (30) covering the metal base (1) as a lid, and an electronic part component arranged at a surface (2i) on the internal space side of the metal lead (2). The internal space is held at an air-tight atmosphere. The metal base (1) has a lower surface

positioned on the same plane as a lower surface of the metal lead (2) or the insulating material (3), the same plane (P) forming a plane to be attached to a mounting board.

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